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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Tongbi Jiang et al.

Serial No.: 09/483,712

Filed: January 14, 2000

For: CHIP-SCALE PACKAGES HAVING
ENCAPSULATED CARRIER BONDS
(As Amended)

Examiner: M. Warren

Group Art Unit: 2815

Attorney Docket No.: 3815US (98-0670)

977/andt C (RE)

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Sir:

The following amendments and remarks are filed in response to the Examiner's remarks in the Final Office Action mailed January 29, 2002, the three-month shortened statutory period for response to which expires on March 29, 2002. This response is submitted on or before two months from the mailing date of the Final Office Action.

IN THE CLAIMS:

Applicants propose to amend claim 1 herein. Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity. Also attached is a version with markings to show the proposed changes made to the claims.